Electronic Pate	nt App	lication Fee	e i ransm	ittai			
Application Number:	100	10613326					
Filing Date:	03-	03-Jul-2003					
Title of Invention:	Vei	Vertical conduction flip-chip device with bump contacts on single surface					
First Named Inventor/Applicant Name:	Da	Daniel M. Kinzer					
Filer:	Ko	Kourosh Salehi/Jane Lim					
Attorney Docket Number:	IR-	IR-2541 DIV					
Filed as Large Entity							
Utility under 35 USC 111(a) Filing Fees							
Description	Description		Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 1 month with \$0 paid		1251	1	130	130		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			130